

PATENT ASSIGNMENT COVER SHEET

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 Stylesheet Version v1.2

EPAS ID: PAT6242748

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
CHUN WEN OOI	04/23/2020
JORGE L. GARCIA	04/22/2020
SIEW IM LOW	04/24/2020
KAY SIANG SIM	06/22/2020
WOOI PING TEOH	04/23/2020
RECEIVING PARTY DATA	
Name:	MOTOROLA SOLUTIONS, INC.
Street Address:	500 W. MONROE STREET
City:	CHICAGO
State/Country:	ILLINOIS
Postal Code:	60661
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	16803135
CORRESPONDENCE DATA	
Fax Number:	(414)277-0656
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
Phone:	414-271-6560
Email:	mkeipdocket@michaelbest.com, MSldocketing@motorolasolutions.com, ectressler@michaelbest.com
Correspondent Name:	MICHAEL BEST & FRIEDRICH LLP (MOTOROLA S
Address Line 1:	790 N. WATER STREET
Address Line 2:	SUITE 2500
Address Line 4:	MILWAUKEE, WISCONSIN 53202
ATTORNEY DOCKET NUMBER:	PAT25226-US-PRI
NAME OF SUBMITTER:	DEREK C. STETTNER
SIGNATURE:	/derek c. stettner/
DATE SIGNED:	08/10/2020
Total Attachments: 6	

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ASSIGNMENT AND AGREEMENT

For good and valuable consideration, the receipt of which is hereby acknowledged, we, **CHUN WEN OOI**, residing in Georgetown, Penang, Malaysia, **JORGE L. GARCIA**, residing in Plantation, State of Florida, United States of America, **SIEW IM LOW**, residing in Pulau Pinang, Penang, Malaysia, **KAY SIANG SIM**, residing in Bayan Lepas, Penang, Malaysia, and **WOI PING TEOH**, residing in Georgetown, Penang, Malaysia, have sold, assigned and transferred, and do hereby sell, assign and transfer, unto MOTOROLA SOLUTIONS, INC., a corporation of the State of Delaware, having its principal office in Chicago, State of Illinois, United States of America, and its successors, assigns, and legal representatives, the entire right, title and interest for the United States of America in and to certain inventions relating to improvements in **PRINTED CIRCUIT BOARD (PCB) CONNECTOR INTERFACE MODULE WITH HEAT AND SCRATCH RESISTANT COVERLAY AND ACCESSORY SYSTEM**, filed on February 27, 2020 as serial number 16/803,135 (Docket No. **PAT25226-US-PRI**), described, illustrated and claimed in an application for Letters Patent of the United States of America executed by us on the dates indicated by our signatures below, together with the entire right, title and interest in and to the application, and in and to Letters Patent which may be issued upon the application, and upon any non-provisional, division, extension, continuation, re-examination, or reissue thereof.

We hereby also sell, assign and transfer unto MOTOROLA SOLUTIONS, INC., the entire right, title and interest in and to the invention and in and to applications for Letters Patent therefor in all countries foreign to the United States of America, including all rights under any and all international conventions and treaties in respect of the invention and the applications for Letters Patent in foreign countries, and we further authorize MOTOROLA SOLUTIONS, INC. to apply for Letters Patent in foreign countries directly in its own name, and to claim priority of the filing date of the application for Letters Patent of the United States of America under the provisions of any and all international conventions and treaties.

We hereby authorize and request the Commissioner of Patents of the United States of America to issue Letters Patent upon the aforesaid application, division, extension, continuation or reissue, to MOTOROLA SOLUTIONS, INC., for the sole use and benefit of MOTOROLA SOLUTIONS, INC., its successors, assigns and legal representatives, to the full end of the term for which Letters Patent may be granted, the same as they would have been held and enjoyed by me had this assignment not been made, and we hereby authorize and request the equivalent authorities in foreign countries to issue the patents of their respective countries to MOTOROLA SOLUTIONS, INC.

We agree that, when requested, we will, without charge to MOTOROLA SOLUTIONS, INC., but at its expense, sign all papers, take all rightful oaths, and do all acts which may be necessary, desirable or convenient for securing and maintaining patents for the inventions in any and all countries and for vesting title thereto in MOTOROLA SOLUTIONS, INC., its successors, assigns and legal representatives or nominees.

We covenant with MOTOROLA SOLUTIONS, INC., its successors, assigns and legal representatives, that the interest and property hereby conveyed is free from all prior assignment, grant, mortgage, license or other encumbrance.

(1) Legal Name of Inventor: **Chun Wen Ooi**

Signature: *Chun Wen Ooi* Date: 23 APRIL 2020

(2) Legal Name of Inventor: **Jorge L. Garcia**

Signature: _____ Date: _____

(3) Legal Name of Inventor: **Siew Im Low**

Signature: _____ Date: _____

(4) Legal Name of Inventor: **Kay Siang Sim**

Signature: _____ Date: _____

(5) Legal Name of Inventor: **Wooi Ping Teoh**

Signature: _____ Date: _____

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(1) Legal Name of Inventor: **Chun Wen Ooi**

Signature: _____ Date: _____

(2) Legal Name of Inventor: **Jorge L. Garcia**

Signature: Jorge L Garcia Date: 4/22/2020

(3) Legal Name of Inventor: **Siew Im Low**

Signature: _____ Date: _____

(4) Legal Name of Inventor: **Kay Siang Sim**

Signature: _____ Date: _____

(5) Legal Name of Inventor: **Wooi Ping Teoh**

Signature: _____ Date: _____

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(1) Legal Name of Inventor: **Chun Wen Ooi**

Signature: _____ Date: _____

(2) Legal Name of Inventor: **Jorge L. Garcia**

Signature: _____ Date: _____

(3) Legal Name of Inventor: **Siew Im Low**

Signature: /LOW SIEW IM/ Date: 24 APR 2020

(4) Legal Name of Inventor: **Kay Siang Sim**

Signature: _____ Date: _____

(5) Legal Name of Inventor: **Wooi Ping Teoh**

Signature: _____ Date: _____

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(1) Legal Name of Inventor: **Chun Wen Ooi**

Signature: _____ Date: _____

(2) Legal Name of Inventor: **Jorge L. Garcia**

Signature: _____ Date: _____

(3) Legal Name of Inventor: **Siew Im Low**

Signature: _____ Date: _____

(4) Legal Name of Inventor: **Kay Siang Sim**

Signature: *KS* Date: 22-June-2020

(5) Legal Name of Inventor: **Wooi Ping Teoh**

Signature: _____ Date: _____

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Signature: _____ Date: _____

(2) Legal Name of Inventor: **Jorge L. Garcia**

Signature: _____ Date: _____

(3) Legal Name of Inventor: **Siew Im Low**

Signature: _____ Date: _____

(4) Legal Name of Inventor: **Kay Siang Sim**

Signature: _____ Date: _____

(5) Legal Name of Inventor: **Wooi Ping Teoh**

Signature: / Teoh Wooi Ping / Date: 23 - April - 2020